



Vishay General Semiconductor

Photovoltaic Solarcell Protection Schottky Rectifier

High Barrier Technology for Improved High Temperature Performance

This datasheet reflects specifications of product in actual application.



P600

FEATURES

- · Guardring for overvoltage protection
- · Low forward voltage drop, low power losses
- · High efficiency operation
- High forward surge capability
- Solder dip 275 °C max. 10 s, per JESD 22-B106
- Compliant to RoHS directive 2002/95/EC and in accordance to WEEE 2002/96/EC

TYPIC	٩L	APP	LIC	ATIONS	3
For use	in	solar	cell	junction	k

box as a bypass diode for protection, using DC forward current without reverse bias.

MECHANICAL DATA

Case: P600, molded epoxy over passivated junction Molding compound meets UL 94 V-0 flammability rating Base P/N-E3 - RoHS compliant, commercial grade

Terminals: Matte tin plated leads, solderable per

J-STD-002 and JESD 22-B102

E3 suffix meets JESD 201 class 1A whisker test Polarity: Color band denotes cathode end

$I_{F(AV)}$	15 A			
V_{RRM}	45 V			
I _{FSM}	300 A			
V_F at $I_F = 15 A$	0.46 V			
T _{OP} max.	175 °C			

PRIMARY CHARACTERISTICS

MAXIMUM RATINGS (T _A = 25 °C unless otherwise noted)					
PARAMETER	SYMBOL	SB15H45	UNIT		
Maximum repetitive peak reverse voltage	V_{RRM}	45	V		
Maximum average forward rectified current (fig. 1)	I _{F(AV)} (1)	15	A		
	I _{F(AV)} (2)	7			
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}	300	Α		
Operating junction and storage temperature range	T _{OP} , T _{STG}	- 55 to + 175	°C		
Junction temperature in DC forward current without reverse bias, $t \le 1$ h (fig. 1)	T ^J (3)	≤ 200	°C		

Notes

- (1) With heatsink, T_L = 25 °C
- (2) Without heatsink, free air
- (3) Meets the requirements of IEC 61215 ed. 2 bypass diode thermal test

SB15H45

Vishay General Semiconductor



ELECTRICAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	I _F = 5 A	T _A = 25 °C	V _F ⁽¹⁾	0.48	-	. V
	I _F = 7.5 A			0.50	-	
	I _F = 15 A			0.56	0.64	
	I _F = 5 A	T _A = 125 °C		0.35	-	
	I _F = 7.5 A			0.39	-	
	I _F = 15 A			0.46	0.54	
Reverse current	V _R = 45 V	T _A = 25 °C	°C I _B ⁽²⁾	10	300	μΑ
	v _R = 45 v	T _A = 125 °C	I R ^(−)	8	20	mA
Typical junction capacitance	4.0 V, 1 MHz		CJ	1020	-	pF

Notes

(1) Pulse test: 300 µs pulse width, 1 % duty cycle

(2) Pulse test: 10 ms pulse width

THERMAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)				
PARAMETER	SYMBOL	SB15H45	UNIT	
Thermal resistance	R ₀ JA (1)	66	°C/W	
	R _{0JL} (1)	14		
Typical thermal resistance	R _{0JL} (2)	3.5	°C/W	

Notes

 $^{(2)}$ T_A = 75 °C, T_L = 125 °C, T_J = 175 °C, infinite mass at 0.375" (9.5 mm) lead length

ORDERING INFORMATION (Example)						
PREFERRED P/N	UNIT WEIGHT (g)	HT (g) PREFERRED PACKAGE CODE BASE QUANTITY DELIVERY MODE				
SB15H45-E3/54	1.756	54	800	13" diameter paper tape and reel		

RATINGS AND CHARACTERISTICS CURVES

(T_A = 25 °C unless otherwise noted)

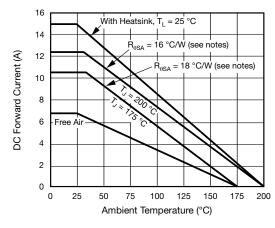


Fig. 1 - Forward Current Derating Curve

Notes

Mounted on junction box

Using DC forward current

Junction box SA (sink to ambient)

Assumes $R_{\theta LS}$ (lead to sink) of 5 $^{\circ}\text{C/W}$

Thermal resistance $R_{\theta SA}$ (sink to ambient):

$$R_{\theta SA} = \frac{(T_J - T_A)}{P_D} - (R_{\theta JL} + R_{\theta LS})$$

 P_D : Power dissipation $P_D = V_F \times I_F$

⁽¹⁾ Without heatsink, free air



Vishay General Semiconductor

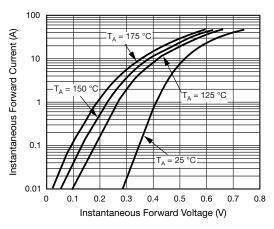


Fig. 2 - Typical Instantaneous Forward Characteristics

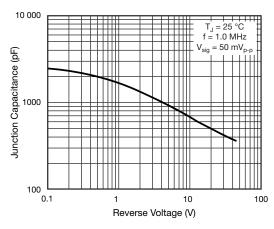


Fig. 4 - Typical Junction Capacitance

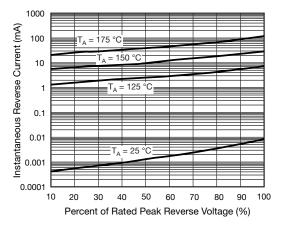
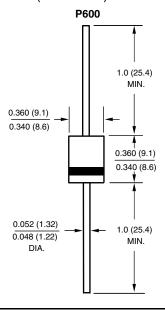


Fig. 3 - Typical Reverse Characteristics

PACKAGE OUTLINE DIMENSIONS in inches (millimeters)





Vishay

Disclaimer

All product specifications and data are subject to change without notice.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained herein or in any other disclosure relating to any product.

Vishay disclaims any and all liability arising out of the use or application of any product described herein or of any information provided herein to the maximum extent permitted by law. The product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein, which apply to these products.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications unless otherwise expressly indicated. Customers using or selling Vishay products not expressly indicated for use in such applications do so entirely at their own risk and agree to fully indemnify Vishay for any damages arising or resulting from such use or sale. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

Product names and markings noted herein may be trademarks of their respective owners.

Revision: 18-Jul-08

Document Number: 91000 www.vishay.com